

## N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY							
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)				
30	0.022 at V <sub>GS</sub> = 4.5 V	6.8	10 nC				
30	0.027 at V <sub>GS</sub> = 2.5 V	6.0	TOTIC				

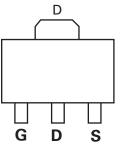
### **FEATURES**

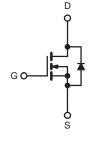
- Halogen-free
- TrenchFET<sup>®</sup> Power MOSFET

### **APPLICATIONS**

· Load Switches for Portable Devices







N-Channel MOSFET

ABSOLUTE MAXIMUM RATIN	<b>IGS</b> T <sub>A</sub> = 25 °C,	unless other	wise noted	
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		6.8 <sup>a</sup>	
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 70 °C		6 <sup>a</sup>	
Continuous Drain Current (1) = 150°C)	T <sub>A</sub> = 25 °C		6.8 <sup>a, b, c</sup>	
	T <sub>A</sub> = 70 °C		6 <sup>a, b, c</sup>	A
Pulsed Drain Current	I <sub>DM</sub>	30		
Continuous Source-Drain Diode Current $T_{C} = 25$		I <sub>S</sub> –	5.2	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	'S	2.1 <sup>b, c</sup>	
	T <sub>C</sub> = 25 °C		6.3	
Movimum Dower Dissinction	T <sub>C</sub> = 70 °C	P <sub>D</sub>	4	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	'D	2.5 <sup>b, c</sup>	vv
	T <sub>A</sub> = 70 °C		1.6 <sup>b, c</sup>	
Operating Junction and Storage Temperatur	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	<u>.</u>	
Soldering Recommendations (Peak Temperation	ature) <sup>e, f</sup>		260	U

## THERMAL RESISTANCE BATINGS

Parameter	Symbol	Typical	Maximum	Unit						
Maximum Junction-to-Ambient <sup>a, c, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	40	50	°C/W					
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	15	20	0/11					

Notes:

a. Package limited, T<sub>C</sub> = 25 °C.
b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 95 °C/W.

e. See Reliability Manual for profile. The ChipFET is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

f. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

Parameter	unless othe Symbol	Min.	Тур.	Max.	Unit		
Static	• • • • • •	Test Conditions					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			25			
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 4.0		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	0.6		1.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1	μA	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}$	30			A	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 6.3 A		0.022	0.033	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 4.5 A		0.030	0.045		
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 6.3 A		45		S	
Dynamic <sup>b</sup>				1	1		
Input Capacitance	C <sub>iss</sub>			1200			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		220		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			100			
Takal Qaka Qhanna	0	$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 6.3 \text{ A}$		22	33	nC	
Total Gate Charge	Qg			10	15		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = 10 V, $V_{GS}$ = 4.5 V, $I_D$ = 6.3 A		2.5			
Gate-Drain Charge	Q <sub>gd</sub>			1.7			
Gate Resistance	Rg	f = 1 MHz		2.4		Ω	
Turn-on Delay Time	t <sub>d(on)</sub>			15	25	1	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 1.5 $\Omega$		10	15	- ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 6.7$ A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		35	55		
Fall Time	t <sub>f</sub>			12	20		
Turn-on Delay Time	t <sub>d(on)</sub>			10	15		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 1.5 $\Omega$		12	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 6.7 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 1 $\Omega$		25	40		
Fall Time	t <sub>f</sub>			10	15		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			5.2	A	
Pulse Diode Forward Current	I <sub>SM</sub>				30	Л	
Body Diode Voltage	V <sub>SD</sub>	$I_{S} = 6.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			20	40	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 6.7 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		10	20	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$r_{\rm F} = 0.1$ A, $u_{\rm F} u_{\rm F} = 100$ A/ $\mu_0$ , $r_{\rm J} = 20$ C		10		200	
Reverse Recovery Rise Time	t <sub>b</sub>			10		ns	

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %

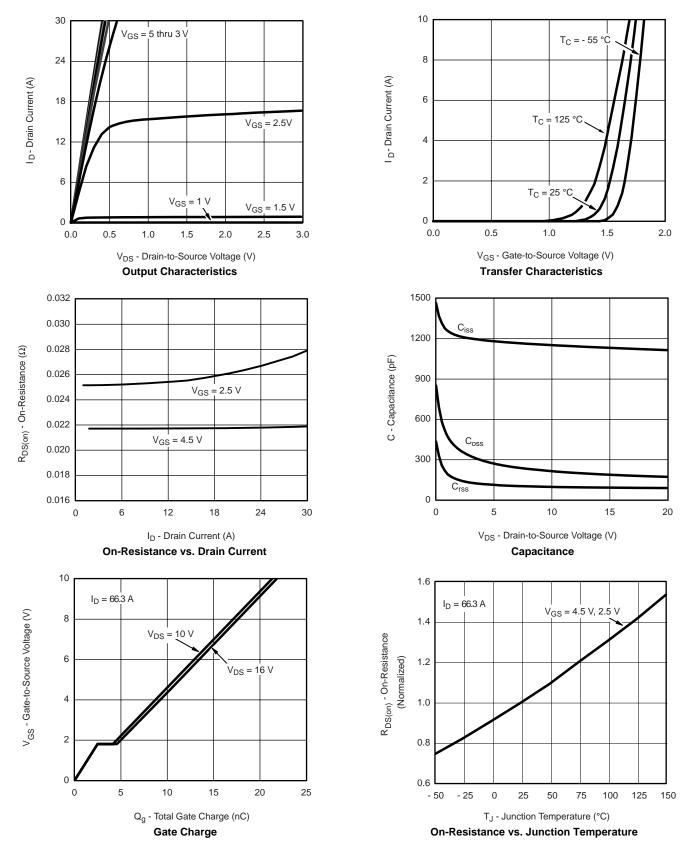
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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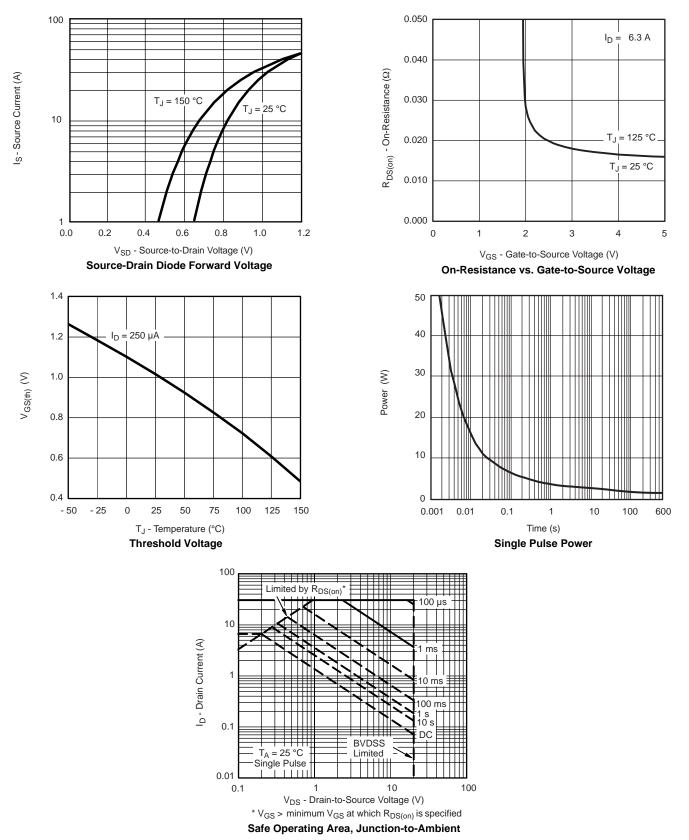


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



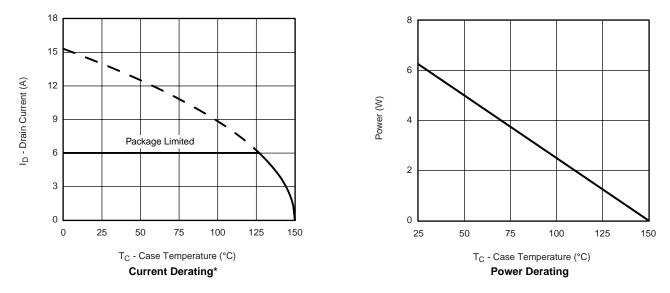








### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

#### 2 1 Duty Cycle = 0.5 + + + + + + 0.2 ffecti П Notes: 0.1 4 P<sub>DM</sub> 0.1 0.05 t<sub>1</sub> t<sub>2</sub> ++-t<sub>1</sub> 0.02 1. Duty Cycle, D = t2 2. Per Unit Base = RthJA 80 °C/W 3. $T_{JM} - T_A = P_{DM}Z_{thJA}^{(t)}$ Single Pulse 4. Surface Mounted 0.01 10<sup>-3</sup> 10-4 10<sup>-2</sup> 10-1 10 100 600 1 Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Ambient 2 1 Duty Cycle = 0.5 Normalized Effective Transient Thermal Impedance $\square$ 0.2 0.1 0.1 0.05 0.02 Single Pulse 0.01 10<sup>-1</sup> 10<sup>-3</sup> 10-2 10-4 1 10 Square Wave Pulse Duration (s)

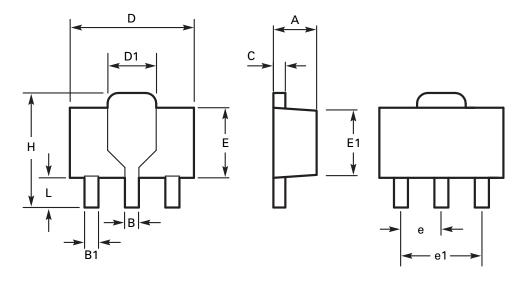
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







## Package outline - SOT89



DIM	Millim	neters	Inc	Inches DIM Millimeters Inch		Millimeters		hes	
	Min	Max	Min	Мах		Min	Мах	Min	Мах
Α	1.40	1.60	0.550	0.630	E	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50 BSC		0.059 BSC	
С	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118 BSC	
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.62	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches



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